

**■ Features**

- SMD construction, and low profile.
- High Impedance and Excellent Frequency Characteristic.
- Self Electromagnetic Shielding.
- Low Magnetic Flux Leakage.

**■ Applications**

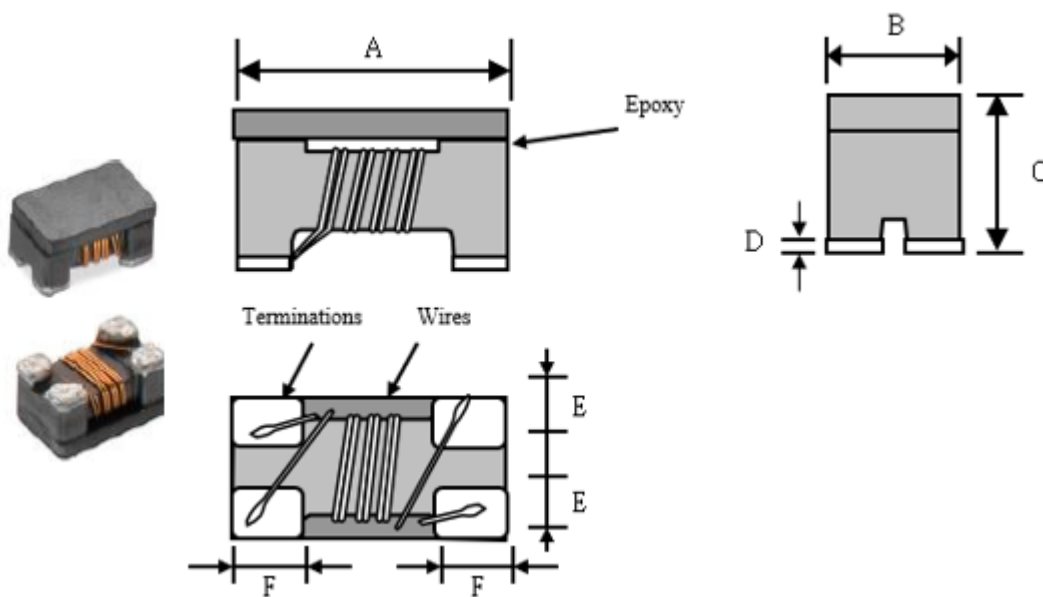
- LED Light, TV game, Monitor, etc.
- EMI common-mode noise.

**■ Product Identification**

$\frac{\text{YPCM}}{(1)}$      $\frac{\square\square\square\square}{(2)}$      $\frac{-\square\square\square}{(3)}$      $\frac{T}{(4)}$

- (1) : Type
- (2) : Dimensions
- (3) : Impedance
- (4) : Taping

**■ Shapes and Dimensions (Unit: mm)**



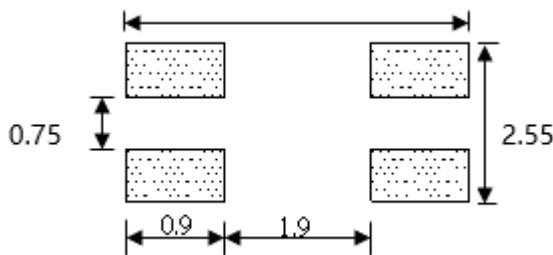
TYPE	A	B	C	D	E Typ.	F Typ.
YPCM3225A	3.2±0.2	2.5±0.2	1.9±0.2	0.2±0.1	0.80	0.65

## Electrical Characteristics

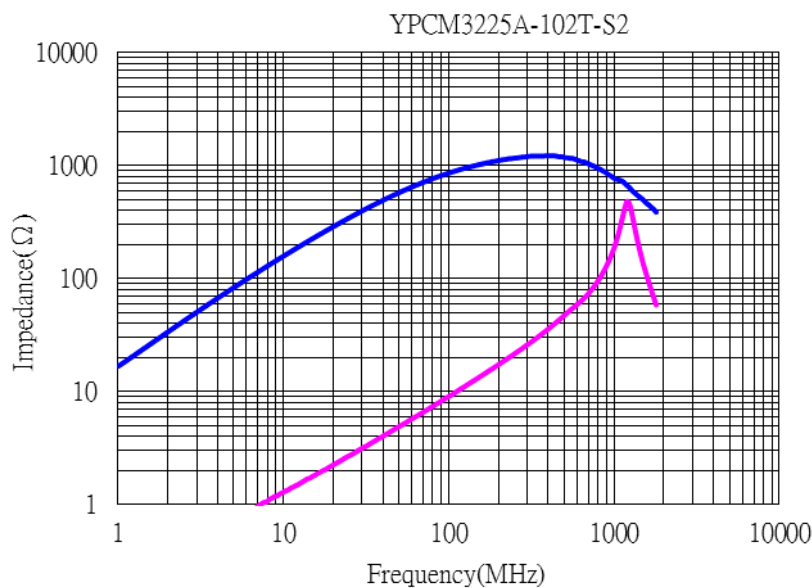
Part Number	Z(Ω) Common mode Impedance @100MHz	DCR (Ω) Max.	Rated current Idc(A) Max.	Rated Voltage Vdc (V)Typical	Insulation Resistance IR (MΩ)Min.
YPCM3225A-102T-S2	1000±25%	0.050	1.5	70	10

- ※ Operating Temperature: -40°C to +85°C
- ※ Storage Temperature and humidity: -20°C up to +40°C, 75% RH max.
- ※ Typical Heat Rating DC Current would cause an approximately ΔT of 40°C
- ※ If Use Wave soldering is there will be some risk. Re-flow soldering temperatures below 240 degrees, there will be unwitting risk.

## Recommended Footprint(mm)



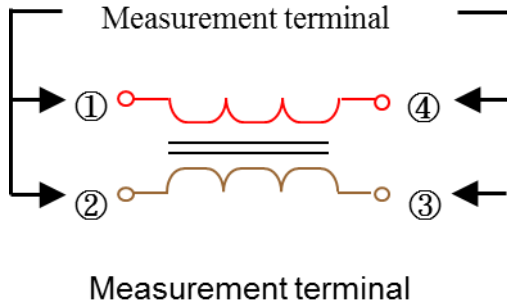
## Performance Curves



## ■ Test Equipment

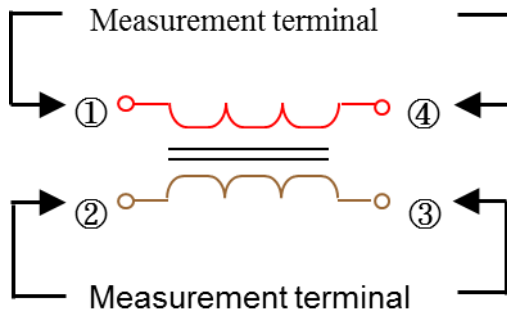
Impedance

Measured by using Agilent 4291A RF Impedance Analyzer.



DC Resistance

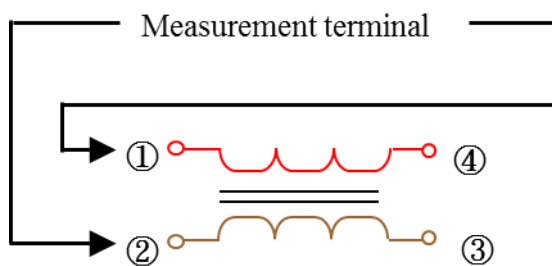
Measured by using Chroma 16502 mill ohm meter.



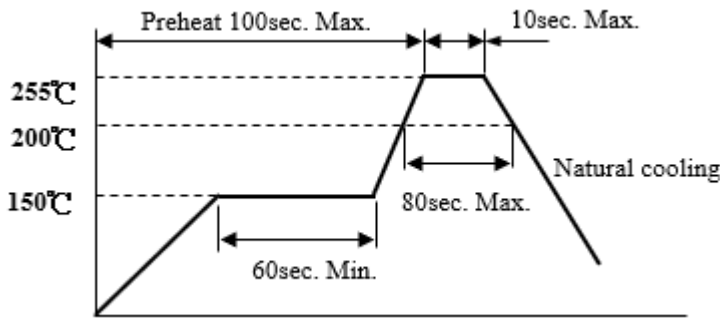
Insulation Resistance

Measured by using Chroma 19073

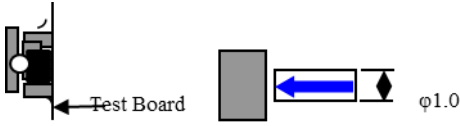
Measurement voltage : 50v , Measurement time : 60 sec.



**Recommended Soldering temp.graph**



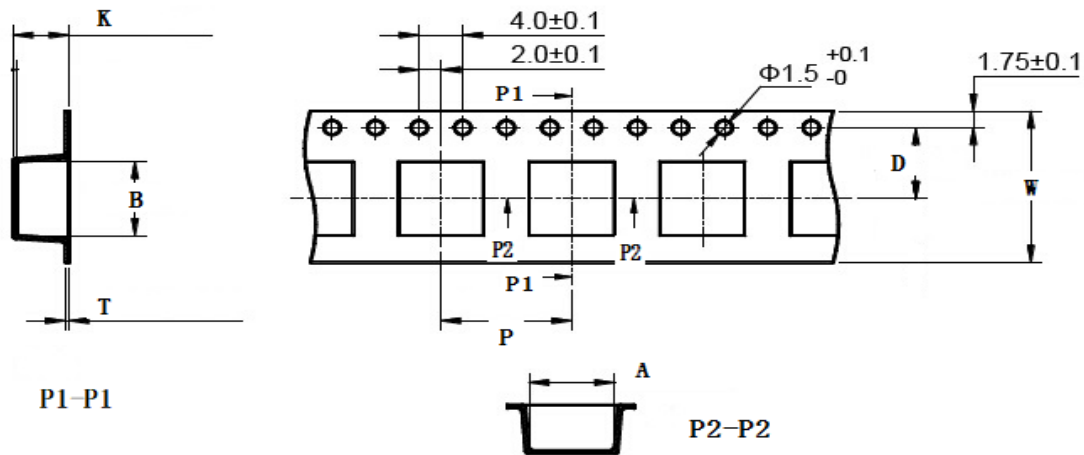
**Mechanical Reliability**

Test	Method Used	Specification & Requirement										
Solderability	Solder heat proof: Preheating: 150 ±10°C 60 seconds Soldering: 245 ±5°C for 4 ±1 sec	The surface of terminal/pin tested shall be covered with new solder by 90%										
Solder Heat Resistance	Preheating:150°C 60secs Solder temperature: 260±5°C Flux:rosin Dip time:10±0.5 secs	Components should have not evidence of electrical and mechanical damage Impedance:within ±15% of initial value										
Terminal strength	Solder a chip to test substrate and then laterally apply a force in the arrow direction 	<table border="1"> <thead> <tr> <th>Series No.</th> <th>F (Kg)</th> </tr> </thead> <tbody> <tr> <td>1608</td> <td>0.5</td> </tr> <tr> <td>2012</td> <td>0.5</td> </tr> <tr> <td>3216</td> <td>1.0</td> </tr> <tr> <td>3225</td> <td>1.0</td> </tr> </tbody> </table>	Series No.	F (Kg)	1608	0.5	2012	0.5	3216	1.0	3225	1.0
Series No.	F (Kg)											
1608	0.5											
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**Endurance Reliability**

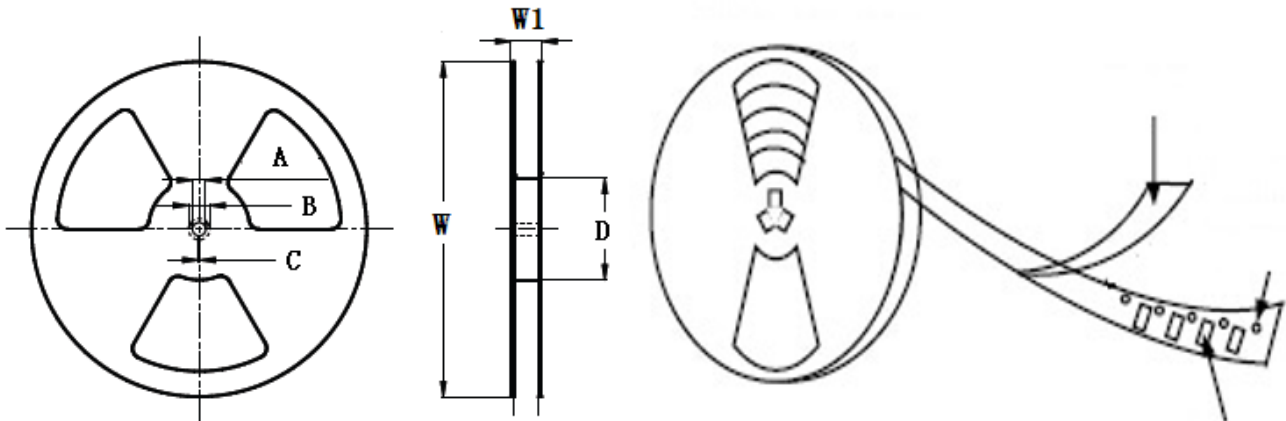
Test	Method Used	Specification & Requirement
Thermal Shock Test	-65°C, (30 mins) -> room temp. (2 mins) -> 125°C, (30 mins) -> room temp. (2 mins) 50 cycles	Impedance change within ± 15% Without mechanical damage
High Temperature Exposure	Apply IDC current @ 60°C ambient Humidity: 90% Duration: 168 hrs	Impedance change within ± 15% Without mechanical damage
Low Temp. Storing	Storing Temp. -40 ±2 °C for total 168 +5/-0 hours	Impedance change within ± 15% Without mechanical damage
High Temp. Storing	Storing Temp. 125 ±2 °C for total 168 +5/-0 hours	Impedance change within ± 15% Without mechanical damage

**■ Taping Dimensions(Unit:mm)**



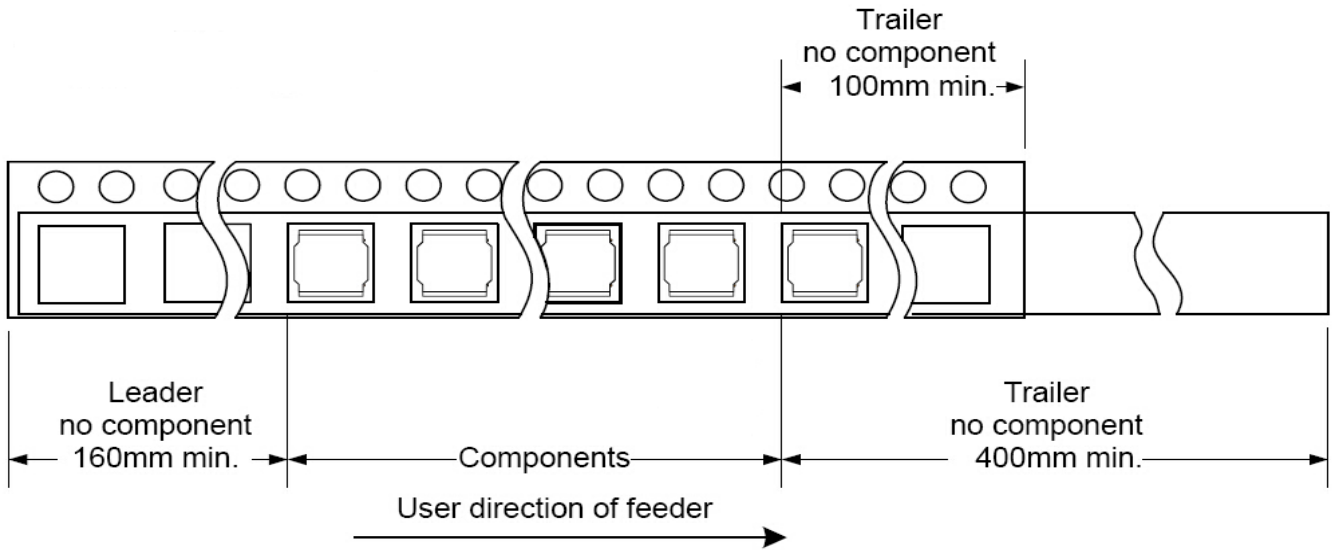
TYPE	W	A	B	D	P	K Max	T Max	MPQ
YPCM3225A	8.00	2.80	3.60	3.50	4.00	2.30	0.25	1000

**■ Reel Dimensions(Unit:mm)**

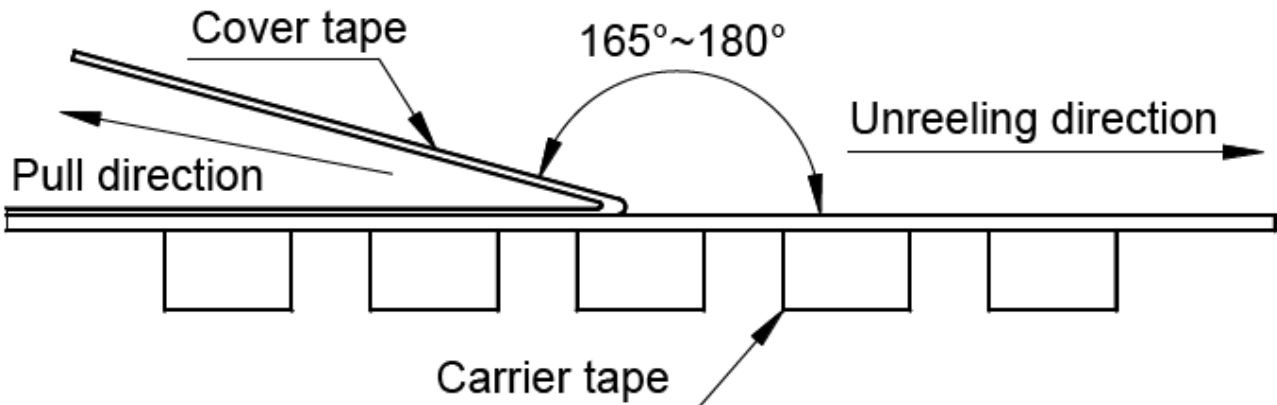


TYPE	W	W1	A	B	C	D
YPCM3225A	178±2.0	8.40±1.50	4.3±0.20	5.0±0.10	3.0±0.10	58±2.0

**Direction of rolling**



**Cover tape peel off condition**



Cover tape peel force shall be 0.1N to 1.3N.

Reference peel speed 300±10mm/min.